



Multimedia Available: Applied Materials Extends Copper/Low k Leadership with Innovative CMP Technology

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--(BUSINESS WIRE)--

Applied Materials, Inc. announces Reflexion(R) LK, the industry's only low down force, high throughput CMP (chemical mechanical polishing) system that enables chipmakers to planarize a wide range of low k and ultra-low k dielectric materials for manufacturing faster 65nm and below copper chip designs. The 300mm Reflexion LK is also suitable for today's high-volume production lines, allowing customers to extend the system's value through multiple device generations.

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